NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Leads 1, 2, 3 may be wider than leads 4, 5, 6 for package orientation.
⚠ Falls within JEDEC MO-178 Variation AB, except minimum lead width.
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